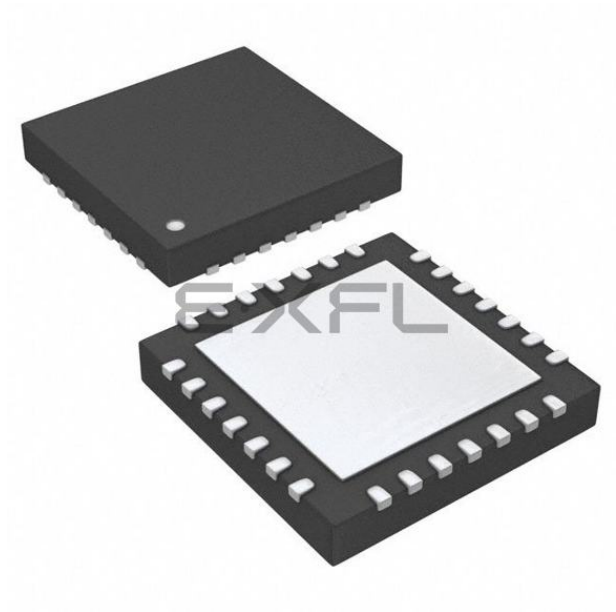

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1936-e-ml

TABLE 1-2: PIC16(L)F1934/6/7 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/C12IN0-/C2OUT(1)/ SRNQ(1)/$\overline{SS}$(1)/VCAP(2)/SEG12	RA0	TTL	CMOS	General purpose I/O.
	AN0	AN	—	A/D Channel 0 input.
	C12IN0-	AN	—	Comparator C1 or C2 negative input.
	C2OUT	—	CMOS	Comparator C2 output.
	SRNQ	—	CMOS	SR Latch inverting output.
	$\overline{SS}$	ST	—	Slave Select input.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F1934/6/7 only).
	SEG12	—	AN	LCD Analog output.
RA1/AN1/C12IN1-/SEG7	RA1	TTL	CMOS	General purpose I/O.
	AN1	AN	—	A/D Channel 1 input.
	C12IN1-	AN	—	Comparator C1 or C2 negative input.
	SEG7	—	AN	LCD Analog output.
RA2/AN2/C2IN+/VREF-/ DACOUT/COM2	RA2	TTL	CMOS	General purpose I/O.
	AN2	AN	—	A/D Channel 2 input.
	C2IN+	AN	—	Comparator C2 positive input.
	VREF-	AN	—	A/D Negative Voltage Reference input.
	DACOUT	—	AN	Voltage Reference output.
	COM2	—	AN	LCD Analog output.
RA3/AN3/C1IN+/VREF+/ COM3(3)/SEG15	RA3	TTL	CMOS	General purpose I/O.
	AN3	AN	—	A/D Channel 3 input.
	C1IN+	AN	—	Comparator C1 positive input.
	VREF+	AN	—	A/D Voltage Reference input.
	COM3(3)	—	AN	LCD Analog output.
	SEG15	—	AN	LCD Analog output.
RA4/C1OUT/CPS6/T0CKI/SRQ/ CCP5/SEG4	RA4	TTL	CMOS	General purpose I/O.
	C1OUT	—	CMOS	Comparator C1 output.
	CPS6	AN	—	Capacitive sensing input 6.
	T0CKI	ST	—	Timer0 clock input.
	SRQ	—	CMOS	SR Latch non-inverting output.
	CCP5	ST	CMOS	Capture/Compare/PWM5.
	SEG4	—	AN	LCD Analog output.
RA5/AN4/C2OUT(1)/CPS7/ SRNQ(1)/$\overline{SS}$(1)/VCAP(2)/SEG5	RA5	TTL	CMOS	General purpose I/O.
	AN4	AN	—	A/D Channel 4 input.
	C2OUT	—	CMOS	Comparator C2 output.
	CPS7	AN	—	Capacitive sensing input 7.
	SRNQ	—	CMOS	SR Latch inverting output.
	$\overline{SS}$	ST	—	Slave Select input.
	VCAP	Power	Power	Filter capacitor for Voltage Regulator (PIC16F1934/6/7 only).
	SEG5	—	AN	LCD Analog output.

Legend: AN = Analog input or output CMOS = CMOS compatible input or output OD = Open Drain
TTL = TTL compatible input ST = Schmitt Trigger input with CMOS levels I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage XTAL = Crystal

Note 1: Pin function is selectable via the APFCON register.
2: PIC16F1934/6/7 devices only.
3: PIC16(L)F1936 devices only.
4: PORTD is available on PIC16(L)F1934/7 devices only.
5: RE<2:0> are available on PIC16(L)F1934/7 devices only.

FIGURE 3-6: ACCESSING THE STACK EXAMPLE 2

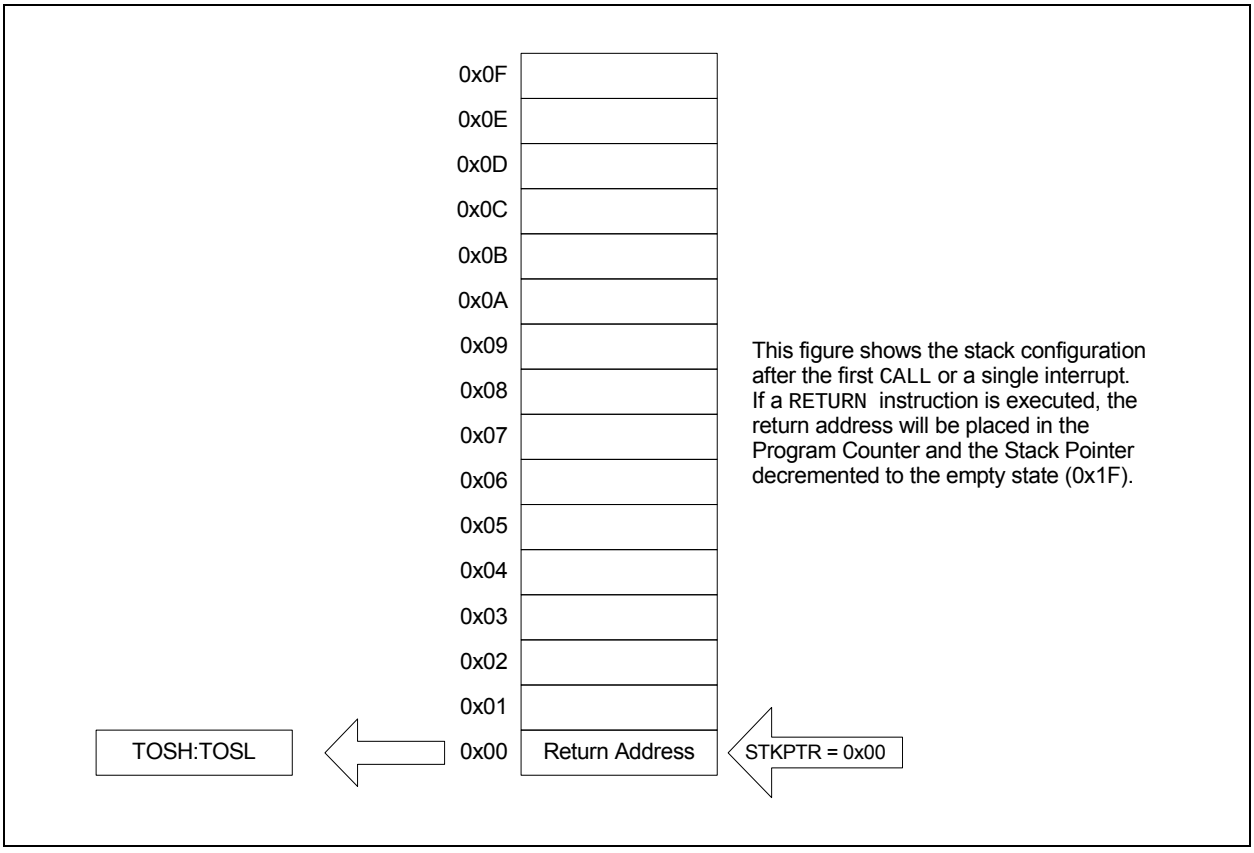
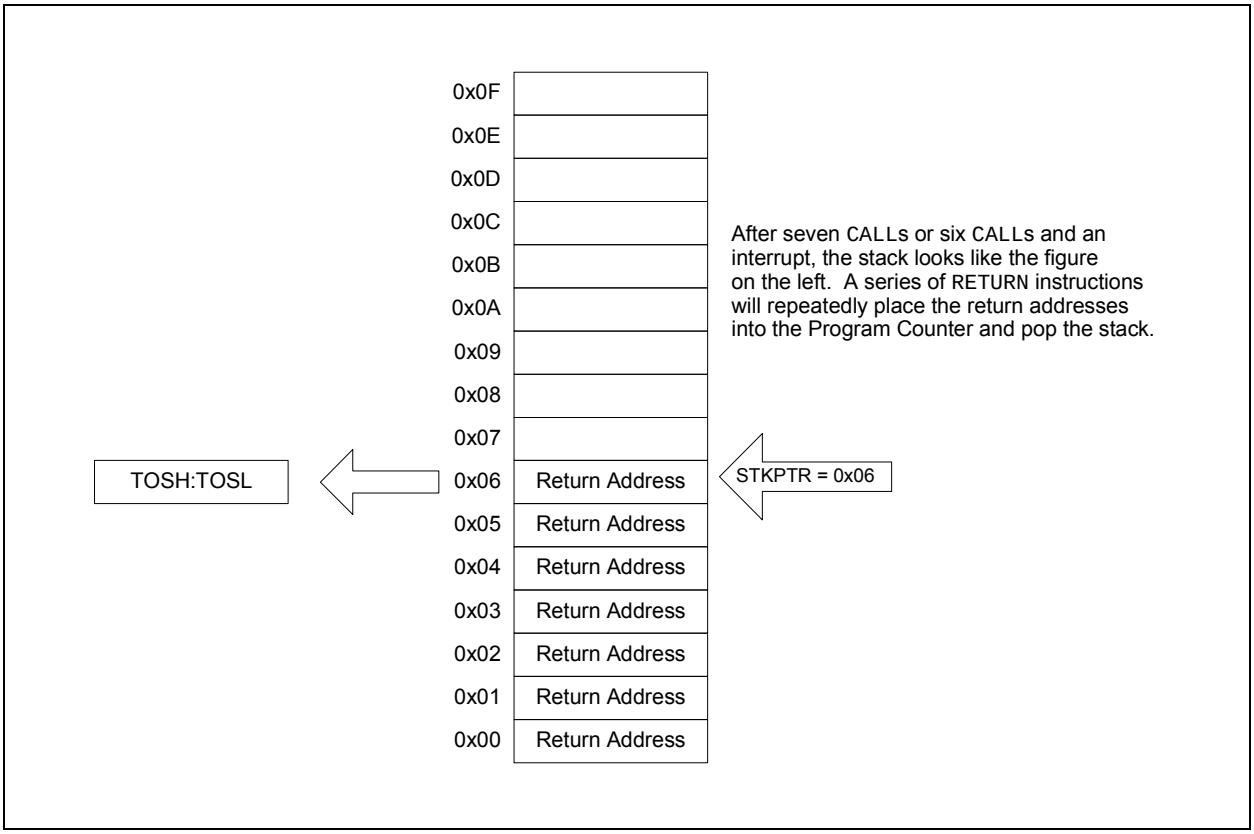


FIGURE 3-7: ACCESSING THE STACK EXAMPLE 3



4.5 Device ID and Revision ID

The memory location 8006h is where the Device ID and Revision ID are stored. The upper nine bits hold the Device ID. The lower five bits hold the Revision ID. See **Section 11.5 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the Device ID and Revision ID.

REGISTER 4-3: DEVICEID: DEVICE ID REGISTER(1)

R	R	R	R	R	R	R
DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	DEV2
bit 13						bit 7

R	R	R	R	R	R	R
DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 6						bit 0

Legend:		U = Unimplemented bit, read as '0'
R = Readable bit	W = Writable bit	'0' = Bit is cleared
-n = Value at POR	'1' = Bit is set	x = Bit is unknown

bit 13-5 **DEV<8:0>:** Device ID bits
100011010 = PIC16F1934
100011011 = PIC16F1936
100011100 = PIC16F1937
100100010 = PIC16LF1934
100100011 = PIC16LF1936
100100100 = PIC16LF1937

bit 4-0 **REV<4:0>:** Revision ID bits
These bits are used to identify the revision.

Note 1: This location cannot be written.

7.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIE1**,** PIE2 and PIE3 registers)

The INTCON, PIR1, PIR2 and PIR3 registers record individual interrupts via interrupt flag bits. Interrupt flag bits will be set, regardless of the status of the GIE, PEIE and individual interrupt enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- Critical registers are automatically saved to the shadow registers (See **Section 7.5 "Automatic Context Saving"**)
- PC is loaded with the interrupt vector 0004h

The firmware within the Interrupt Service Routine (ISR) should determine the source of the interrupt by polling the interrupt flag bits. The interrupt flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any interrupt that occurs while executing the ISR will be recorded through its interrupt flag, but will not cause the processor to redirect to the interrupt vector.

The `RETFIE` instruction exits the ISR by popping the previous address from the stack, restoring the saved context from the shadow registers and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

Note 1:	Individual interrupt flag bits are set, regardless of the state of any other enable bits.
2:	All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

7.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is 3 or 4 instruction cycles. For asynchronous interrupts, the latency is 3 to 5 instruction cycles, depending on when the interrupt occurs. See Figure 7-2 and Figure 7-3 for more details.

7.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to **Section 9.0 "Power-Down Mode (Sleep)"** for more details.

7.4 INT Pin

The INT pin can be used to generate an asynchronous edge-triggered interrupt. This interrupt is enabled by setting the INTE bit of the INTCON register. The INTEDG bit of the OPTION_REG register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector.

7.5 Automatic Context Saving

Upon entering an interrupt, the return PC address is saved on the stack. Additionally, the following registers are automatically saved in the Shadow registers:

- W register
- STATUS register (except for $\overline{TO}$ and $\overline{PD}$)
- BSR register
- FSR registers
- PCLATH register

Upon exiting the Interrupt Service Routine, these registers are automatically restored. Any modifications to these registers during the ISR will be lost. If modifications to any of these registers are desired, the corresponding Shadow register should be modified and the value will be restored when exiting the ISR. The Shadow registers are available in Bank 31 and are readable and writable. Depending on the user's application, other registers may also need to be saved.

12.0 I/O PORTS

Depending on the device selected and peripherals enabled, there are up to five ports available. In general, when a peripheral is enabled on a port pin, that pin cannot be used as a general purpose output. However, the pin can still be read.

Each port has three standard registers for its operation. These registers are:

- TRISx registers (data direction)
- PORTx registers (reads the levels on the pins of the device)
- LATx registers (output latch)

Some ports may have one or more of the following additional registers. These registers are:

- ANSELx (analog select)
- WPUx (weak pull-up)
- INLVLx (input level control)

TABLE 12-1: PORT AVAILABILITY PER DEVICE

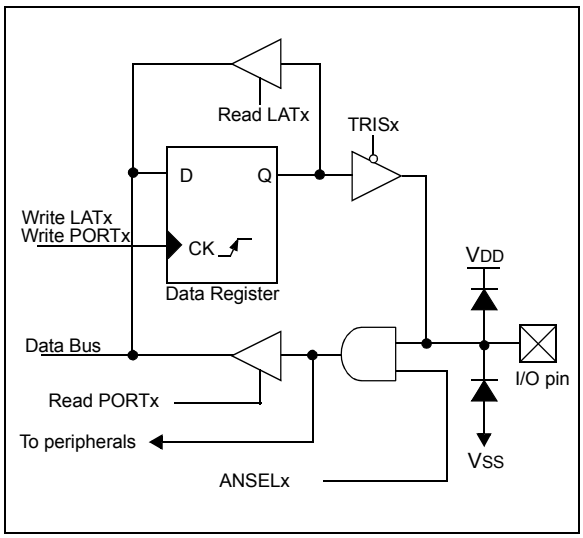
Device	PORTA	PORTB	PORTC	PORTD	PORTE
PIC16(L)F1934	●	●	●	●	●
PIC16(L)F1936	●	●	●		●
PIC16(L)F1937	●	●	●	●	●

The Data Latch (LATx registers) is useful for read-modify-write operations on the value that the I/O pins are driving.

A write operation to the LATx register has the same effect as a write to the corresponding PORTx register. A read of the LATx register reads of the values held in the I/O PORT latches, while a read of the PORTx register reads the actual I/O pin value.

Ports that support analog inputs have an associated ANSELx register. When an ANSEL bit is set, the digital input buffer associated with that bit is disabled. Disabling the input buffer prevents analog signal levels on the pin between a logic high and low from causing excessive current in the logic input circuitry. A simplified model of a generic I/O port, without the interfaces to other peripherals, is shown in Figure 12-1.

FIGURE 12-1: GENERIC I/O PORT OPERATION



EXAMPLE 12-1: INITIALIZING PORTA

```
; This code example illustrates
; initializing the PORTA register. The
; other ports are initialized in the same
; manner.

BANKSEL  PORTA        ;
CLRF     PORTA        ;Init PORTA
BANKSEL  LATA         ;Data Latch
CLRF     LATA         ;
BANKSEL  ANSELA       ;
CLRF     ANSELA       ;digital I/O
BANKSEL  TRISA        ;
MOVLW    B'00111000'  ;Set RA<5:3> as inputs
MOVWF    TRISA        ;and set RA<2:0> as
                      ;outputs
```

TABLE 12-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON	—	CCP3SEL	T1GSEL	P2BSEL	SRNQSEL	C2OUTSEL	SSSEL	CCP2SEL	131
CCPxCON	PxM<1:0>		DCxB<1:0>		CCPxM<3:0>				234
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	142
LCDCON	LCDEN	SLPEN	WERR	—	CS<1:0>		LMUX<1:0>		329
LCDSE0	SE7	SE6	SE5	SE4	SE3	SE2	SE1	SE0	333
LCDSE1	SE15	SE14	SE13	SE12	SE11	SE10	SE9	SE8	333
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	142
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	301
SSPCON1	WCOL	SSPOV	SSPEN	CKP	SSPM<3:0>				287
SSPSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	286
T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	$\overline{T1SYNC}$	—	TMR1ON	203
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	300
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

REGISTER 12-20: LATE: PORTE DATA LATCH REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
—	—	—	—	—	LATE2	LATE1	LATE0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented**: Read as '0'

bit 2-0 **LATE<2:0>**: PORTE Output Latch Value bits(1)

Note 1: Writes to PORTE are actually written to corresponding LATE register. Reads from PORTE register is return of actual I/O pin values.

REGISTER 12-21: ANSELE: PORTE ANALOG SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	ANSE2(2)	ANSE1(2)	ANSE0(2)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **ANSE<2:0>**: Analog Select between Analog or Digital Function on Pins RE<2:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

2: ANSELE register is not implemented on the PIC16(L)F1936. Read as '0'

14.0 FIXED VOLTAGE REFERENCE (FVR)

The Fixed Voltage Reference, or FVR, is a stable voltage reference, independent of VDD, with 1.024V, 2.048V or 4.096V selectable output levels. The output of the FVR can be configured to supply a reference voltage to the following:

- ADC input channel
- ADC positive reference
- Comparator positive input
- Digital-to-Analog Converter (DAC)
- Capacitive Sensing (CPS) module
- LCD bias generator

The FVR can be enabled by setting the FVREN bit of the FVRCON register.

14.1 Independent Gain Amplifiers

The output of the FVR supplied to the ADC, Comparators, DAC and CPS is routed through two independent programmable gain amplifiers. Each amplifier can be configured to amplify the reference voltage by 1x, 2x or 4x, to produce the three possible voltage levels.

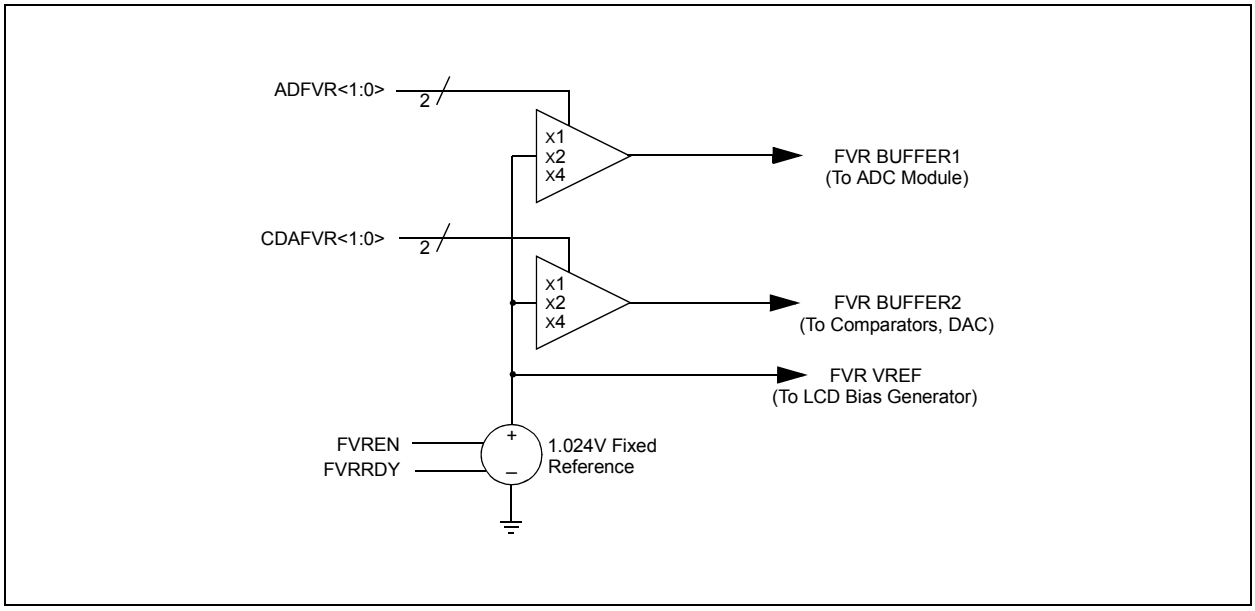
The ADFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the ADC module. Reference **Section 15.0 "Analog-to-Digital Converter (ADC) Module"** for additional information.

The CDAFVR<1:0> bits of the FVRCON register are used to enable and configure the gain amplifier settings for the reference supplied to the DAC, CPS and comparator module. Reference **Section 17.0 "Digital-to-Analog Converter (DAC) Module"**, **Section 18.0 "Comparator Module"** and **Section 26.0 "Capacitive Sensing (CPS) Module"** for additional information.

14.2 FVR Stabilization Period

When the Fixed Voltage Reference module is enabled, it requires time for the reference and amplifier circuits to stabilize. Once the circuits stabilize and are ready for use, the FVRRDY bit of the FVRCON register will be set. See in the applicable Electrical Specifications Chapter for the minimum delay requirement.

FIGURE 14-1: VOLTAGE REFERENCE BLOCK DIAGRAM



REGISTER 23-6: PSTRxCON: PWM STEERING CONTROL REGISTER(1)

U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-1/1
—	—	—	STRxSYNC	STRxD	STRxC	STRxB	STRxA
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **STRxSYNC:** Steering Sync bit
1 = Output steering update occurs on next PWM period
0 = Output steering update occurs at the beginning of the instruction cycle boundary

bit 3 **STRxD:** Steering Enable bit D
1 = PxD pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxD pin is assigned to port pin

bit 2 **STRxC:** Steering Enable bit C
1 = PxC pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxC pin is assigned to port pin

bit 1 **STRxB:** Steering Enable bit B
1 = PxB pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxB pin is assigned to port pin

bit 0 **STRxA:** Steering Enable bit A
1 = PxA pin has the PWM waveform with polarity control from CCPxM<1:0>
0 = PxA pin is assigned to port pin

Note 1: The PWM Steering mode is available only when the CCPxCON register bits CCPxM<3:2> = 11 and PxM<1:0> = 00.

FIGURE 24-17: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 1, DHEN = 1)

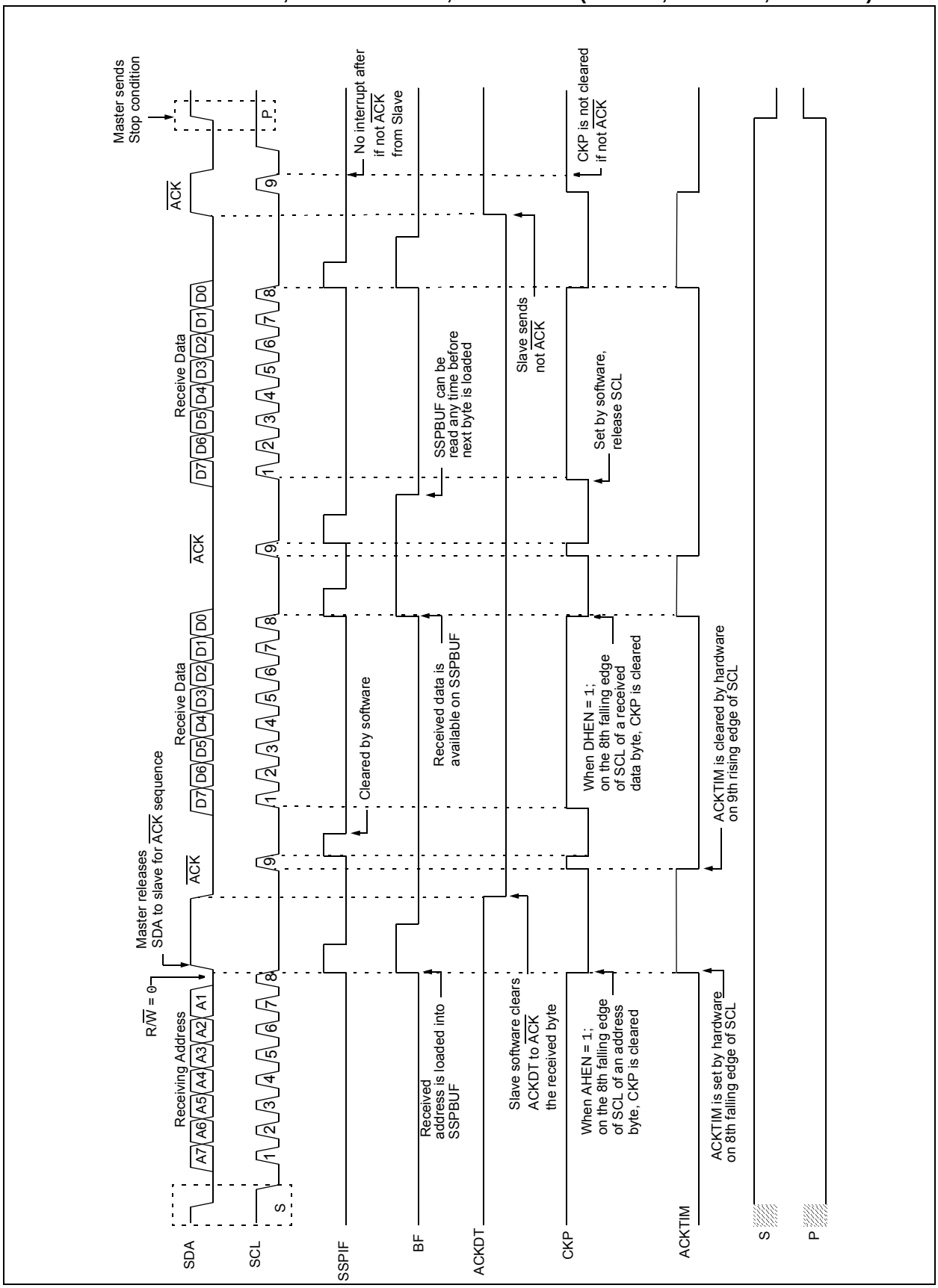


TABLE 25-1: SUMMARY OF REGISTERS ASSOCIATED WITH ASYNCHRONOUS TRANSMISSION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	302
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	98
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	99
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	102
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	301
SPBRGL	BRG<7:0>								303*
SPBRGH	BRG<15:8>								303*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	142
TXREG	EUSART Transmit Data Register								293*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	300

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for Asynchronous Transmission.

* Page provides register information.

25.3.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCON register starts the auto-baud calibration sequence (Figure 25-6). While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Table 25-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRGL register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRGL register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 25-6. During ABD, both the SPBRGH and SPBRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 25.3.3 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

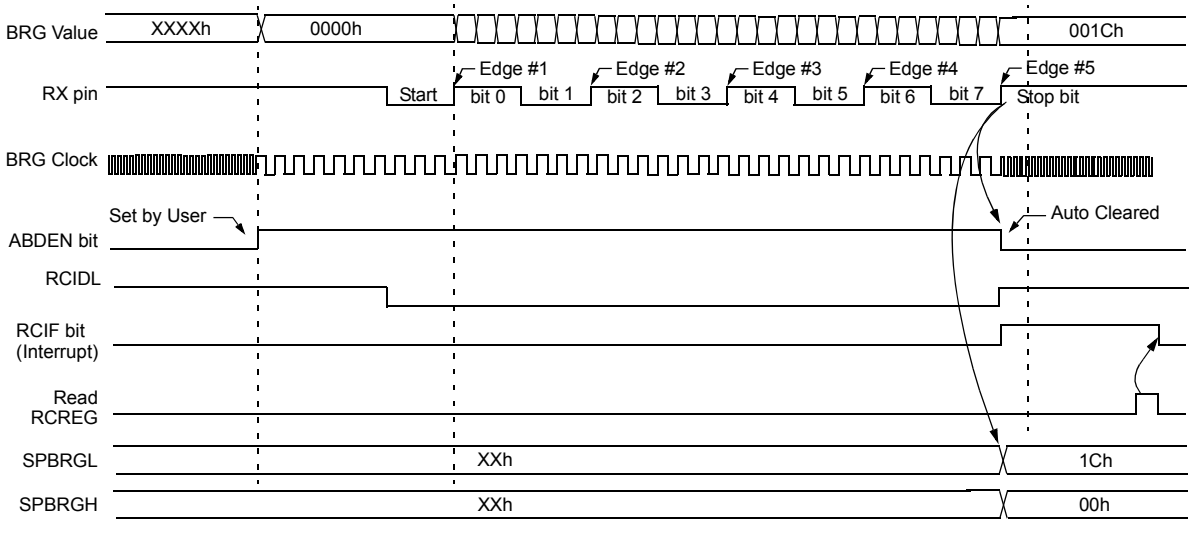
3: During the auto-baud process, the auto-baud counter starts counting at 1. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRGL register pair.

TABLE 25-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SPBRGL and SPBRGH registers are both used as a 16-bit counter, independent of BRG16 setting.

FIGURE 25-6: AUTOMATIC BAUD RATE CALIBRATION



Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode.

27.11 Operation During Sleep

The LCD module can operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Setting the SLPEN bit allows the LCD module to go to Sleep. Clearing the SLPEN bit allows the module to continue to operate during Sleep.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will cease all functions and go into a very low-current Consumption mode. The module will stop operation immediately and drive the minimum LCD voltage on both segment and common lines. Figure 27-20 shows this operation.

The LCD module can be configured to operate during Sleep. The selection is controlled by bit SLPEN of the LCDCON register. Clearing SLPEN and correctly configuring the LCD module clock will allow the LCD module to operate during Sleep. Setting SLPEN and correctly executing the LCD module shutdown will disable the LCD module during Sleep and save power.

If a SLEEP instruction is executed and SLPEN = 1, the LCD module will immediately cease all functions, drive the outputs to Vss and go into a very Low-Current mode. The SLEEP instruction should only be executed after the LCD module has been disabled and the current cycle completed, thus ensuring that there are no DC voltages on the glass. To disable the LCD module, clear the LCDEN bit. The LCD module will complete the disabling process after the current frame, clear the LCDA bit and optionally cause an interrupt.

The steps required to properly enter Sleep with the LCD disabled are:

- Clear LCDEN
- Wait for LCDA = 0 either by polling or by interrupt
- Execute SLEEP

If SLPEN = 0 and SLEEP is executed while the LCD module clock source is FOSC/4, then the LCD module will halt with the pin driving the last LCD voltage pattern. Prolonged exposure to a fixed LCD voltage pattern will cause damage to the LCD glass. To prevent LCD glass damage, either perform the proper LCD module shutdown prior to Sleep, or change the LCD module clock to allow the LCD module to continue operation during Sleep.

If a SLEEP instruction is executed and SLPEN = 0 and the LCD module clock is either T1OSC or LFINTOSC, the module will continue to display the current contents of the LCDDATA registers. While in Sleep, the LCD data cannot be changed. If the LCDIE bit is set, the device will wake from Sleep on the next LCD frame boundary. The LCD module current consumption will not decrease in this mode; however, the overall device power consumption will be lower due to the shutdown of the CPU and other peripherals.

Table 27-8 shows the status of the LCD module during a Sleep while using each of the three available clock sources.

Note:	When the LCDEN bit is cleared, the LCD module will be disabled at the completion of frame. At this time, the port pins will revert to digital functionality. To minimize power consumption due to floating digital inputs, the LCD pins should be driven low using the PORT and TRIS registers.

If a SLEEP instruction is executed and SLPEN = 0, the module will continue to display the current contents of the LCDDATA registers. To allow the module to continue operation while in Sleep, the clock source must be either the LFINTOSC or T1OSC external oscillator. While in Sleep, the LCD data cannot be changed. The LCD module current consumption will not decrease in this mode; however, the overall consumption of the device will be lower due to shut down of the core and other peripheral functions.

Table 27-8 shows the status of the LCD module during Sleep while using each of the three available clock sources:

TABLE 27-8: LCD MODULE STATUS DURING SLEEP

Clock Source	SLPEN	Operational During Sleep
T1OSC	0	Yes
	1	No
LFINTOSC	0	Yes
	1	No
FOSC/4	0	No
	1	No

Note:	The LFINTOSC or external T1OSC oscillator must be used to operate the LCD module during Sleep.

If LCD interrupts are being generated (Type-B waveform with a multiplex mode not static) and LCDIE = 1, the device will awaken from Sleep on the next frame boundary.

30.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.5V
Voltage on V_{CAP} pin with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on $\overline{MCLR}$ with respect to Vss ..... -0.3V to +9.0V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS}(2) pin, -40°C ≤ T_A ≤ +85°C for industrial ..... 255 mA
Maximum current out of V_{SS}(2) pin, -40°C ≤ T_A ≤ +125°C for extended ..... 105 mA
Maximum current into V_{DD}(2) pin, -40°C ≤ T_A ≤ +85°C for industrial ..... 170 mA
Maximum current into V_{DD}(2) pin, -40°C ≤ T_A ≤ +125°C for extended ..... 70 mA
Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OI} \times I_{OL})$

2: For 28-pin devices.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

30.6 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θJA	Thermal Resistance Junction to Ambient	60	°C/W	28-pin SPDIP package
			80	°C/W	28-pin SOIC package
			90	°C/W	28-pin SSOP package
			27.5	°C/W	28-pin UQFN 4x4mm package
			27.5	°C/W	28-pin QFN 6x6mm package
			47.2	°C/W	40-pin PDIP package
			46	°C/W	44-pin TQFP package
			24.4	°C/W	44-pin QFN 8x8mm package
TH02	θJC	Thermal Resistance Junction to Case	31.4	°C/W	28-pin SPDIP package
			24	°C/W	28-pin SOIC package
			24	°C/W	28-pin SSOP package
			24	°C/W	28-pin UQFN 4x4mm package
			24	°C/W	28-pin QFN 6x6mm package
			24.7	°C/W	40-pin PDIP package
			14.5	°C/W	44-pin TQFP package
			20	°C/W	44-pin QFN 8x8mm package
TH03	TJMAX	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = PINTERNAL + PI/O
TH05	PINTERNAL	Internal Power Dissipation	—	W	PINTERNAL = IDD x VDD(1)
TH06	PI/O	I/O Power Dissipation	—	W	PI/O = Σ (IOL * VOL) + Σ (IOH * (VDD - VOH))
TH07	PDER	Derated Power	—	W	PDER = PDMAX (TJ - TA)/θJA(2)

Note 1: IDD is current to run the chip alone without driving any load on the output pins.
2: TA = Ambient Temperature
3: TJ = Junction Temperature

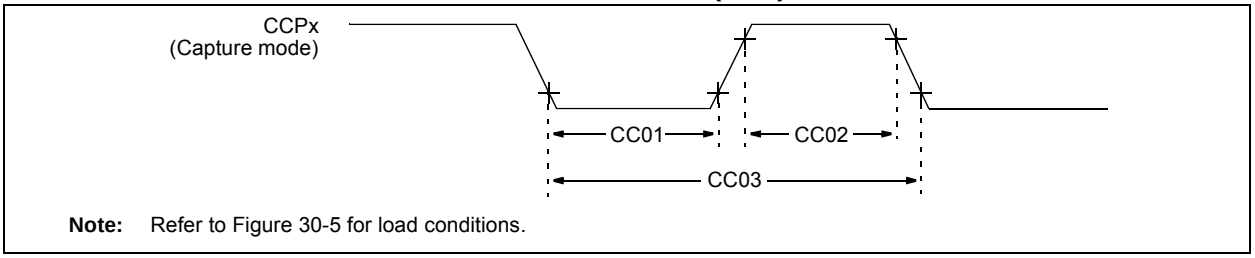
TABLE 30-6: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
48	FT1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 30-11: CAPTURE/COMPARE/PWM TIMINGS (CCP)



Note: Refer to Figure 30-5 for load conditions.

TABLE 30-7: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP)

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
CC01*	TccL	CCPx Input Low Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC02*	TccH	CCPx Input High Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC03*	TccP	CCPx Input Period		3TCY + 40 / N	—	—	ns	N = prescale value (1, 4 or 16)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 31-62: PIC16LF1937 TIMER 1 OSCILLATOR

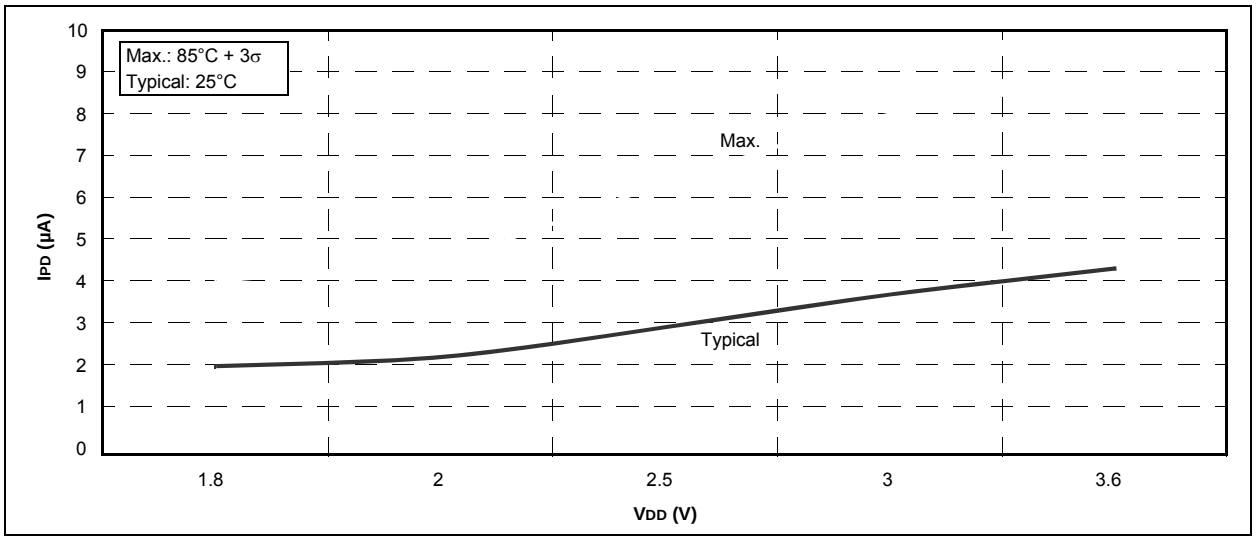


FIGURE 31-63: PIC16F1937 TIMER 1 OSCILLATOR

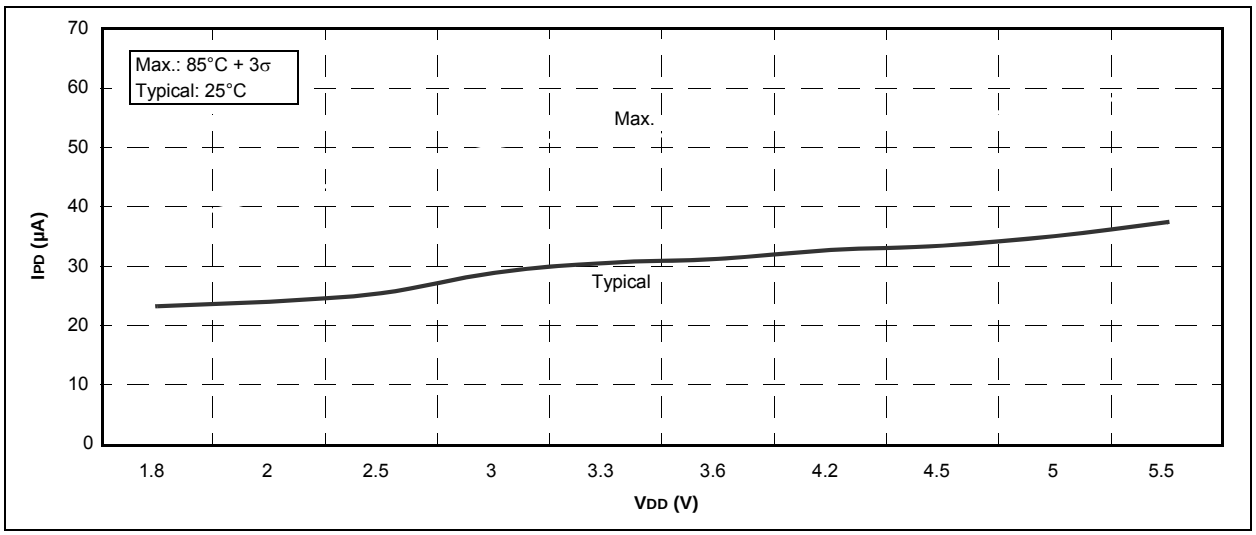
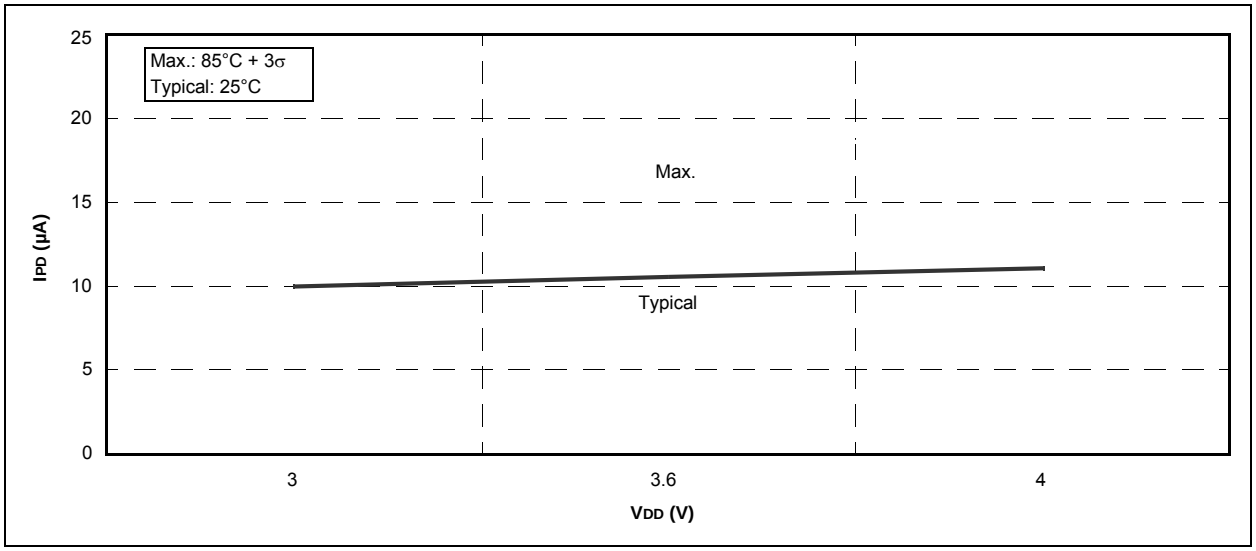


FIGURE 31-64: PIC16LF1937 BOR CURRENT



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